PRE-ENCAPSULATED LEAD FRAMES FOR MICROELECTRONIC DEVICE PACKAGES, AND ASSOCIATED METHODS

ABSTRACT OF THE DISCLOSURE

Pre-encapsulated lead frames suitable for use in microelectronic device packages are disclosed. Individual lead frames can include a set of multiple lead fingers arranged side by side with neighboring lead fingers spaced apart from each other by a corresponding gap. An encapsulating compound at least partially encapsulates the set of lead fingers without encapsulating a microelectronic device. The encapsulating compound can generally fill the plurality of gaps between two adjacent lead fingers.

Figure : 2